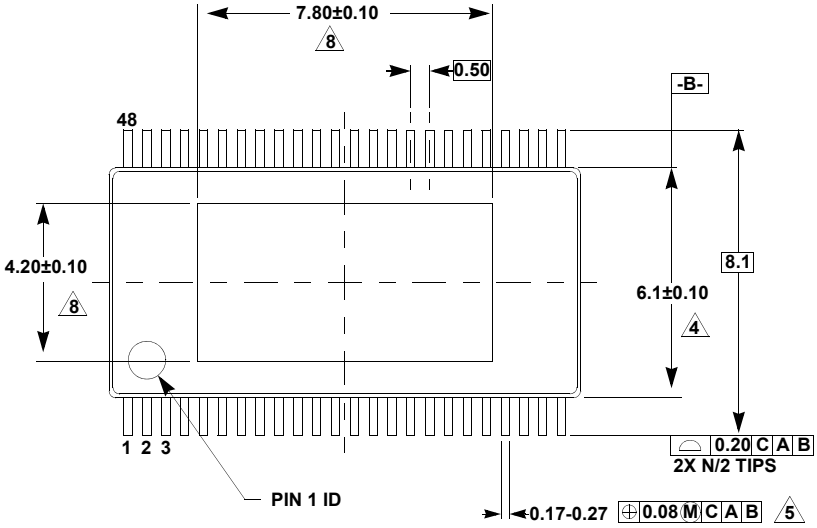
Package Outline Drawing

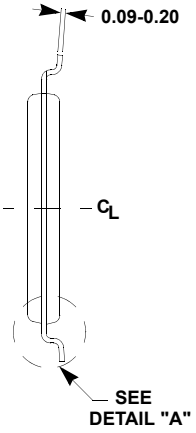
M48.240A

48 LEAD THIN SHRINK SMALL OUTLINE PACKAGE, TSSOP - TOP EXPOSED PAD (TSSOP-TEP)

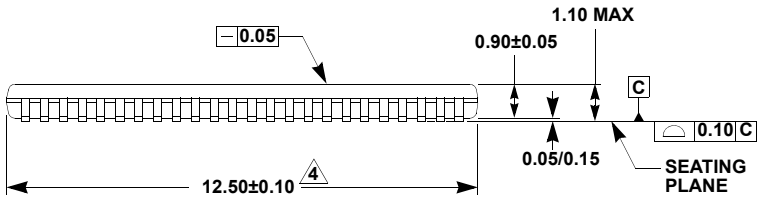
Rev 2, 10/11



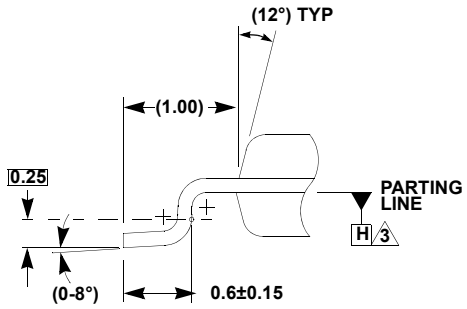
TOP VIEW



BOTTOM VIEW

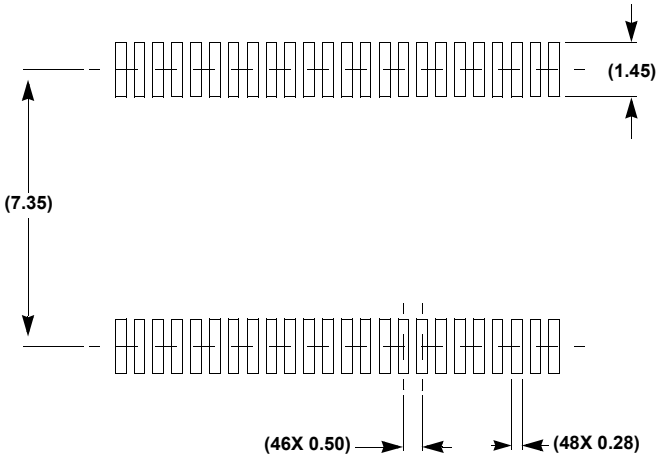


SIDE VIEW



DETAIL "A"

SCALE: (NONE)
(VIEW ROTATED 90° C.W.)



TYPICAL RECOMMENDED LAND PATTERN

NOTES:

1. All dimensions are in millimeters (angles in degrees).
2. Dimensioning & tolerances per ASME. Y14.5m-1994.
3. Datum plane H located at mold parting line and coincident with lead where lead exits plastic body at bottom of parting line.
4. At reference datum and does not include mold flash or protrusions, and is measured at the bottom parting line. Mold flash or protrusions shall not exceed 0.15mm on the package ends and 0.25mm between the leads.
5. The lead width dimension does not include dambar protrusion. Allowable dambar protrusion shall be 0.08mm total in excess of the lead width dimension at maximum material condition. Dambar cannot be located on the lower radius or the foot. Minimum space between protrusions and an adjacent lead should be 0.07mm.
6. This part is compliant with JEDEC specification MO-153 variation EDT except it is 0.1mm thinner.
7. Dimensions in () are for reference only.
8. Dimensions are for top exposed pad.